CM Questionnaire

**PROJECT INFORMATION**

* + Company:
	+ Contact person:
	+ Product name:
	+ RFQ quantity(ies):
	+ Number of production batches:
	+ Desired Date of Delivery:
	+ Urgency (high-normal-low):
	+ Future production batches planned?:

**DESIRED MIKROELEKTRONIKA SERVICES**

* + Electronics design (YES/NO):
	+ PCB design (YES/NO):
	+ BOM components procurement (YES/NO):
	+ PCB production/procurement (YES/NO):
	+ Assembly/board manufacturing (YES/NO):
	+ Testing (YES/NO):
	+ Package (cardbox) creation (YES/NO):

**ADMINISTRATIVE**

* + Bill-To address
		- Company Name:
		- Contact Person:
		- Phone number:
	+ Ship-To address
		- Company Name:
		- Contact Person:
		- Address:
		- Phone number:

**BOM COMPONENTS SPECIFICATION**

* + Are there any critical components?

(if yes, please specify in BOM which)

* + Are there any components with unusual reflow profiles?
	+ Are there any obsolete components?
	+ Are there any hard-to-find components?
	+ Can we suggest uncritical components replacements (e.g. Headers)?

**PCB SPECIFICATION**

* + PCB thickness [mm]:
	+ board material:
	+ number of layers:
	+ layer stackup:
	+ surface finish:
* finished cooper:
	+ solder mask:
	+ legend/silk:
	+ board size:
	+ panelized (yes/no):

**TESTING/PROGRAMMING**

* Prototype already available?
* Testing/programming procedure already available?
* Estimated testing/programming time per board:
* Testing equipment list:

**ADDITIONAL REMARKS**